

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
ATAPOL PRAJUCKAMOL	01/03/2012
BIH WEN FON	01/03/2012
JUN KEAT LEE	01/03/2012
<b>RECEIVING PARTY DATA</b>	
<b>Name:</b>	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
<b>Street Address:</b>	5005 EAST MCDOWELL ROAD
<b>Internal Address:</b>	MD-A700
<b>City:</b>	PHOENIX
<b>State/Country:</b>	ARIZONA
<b>Postal Code:</b>	85008
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
Application Number:	14273785
<b>CORRESPONDENCE DATA</b>	
<b>Fax Number:</b>	(602)244-3169
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
<b>Phone:</b>	602-244-6648
<b>Email:</b>	PATENTS@ONSEMI.COM
<b>Correspondent Name:</b>	SEMICONDUCTOR COMPONENTS INDUSTRIES, LLC
<b>Address Line 1:</b>	5005 E. MCDOWELL ROAD, MAILDROP A700
<b>Address Line 4:</b>	PHOENIX, ARIZONA 85008
<b>ATTORNEY DOCKET NUMBER:</b>	ONS01461D01
<b>NAME OF SUBMITTER:</b>	KELLY A NELSON
<b>SIGNATURE:</b>	/Kelly A. Nelson/
<b>DATE SIGNED:</b>	05/09/2014
<b>Total Attachments: 2</b>	
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source=ONS01461_Assignment#page2.tif	

ATTORNEY DKT#: ONS01461 MALAYSIA  
ASSIGNMENT OF ENTIRE INTEREST IN INVENTION  
BEFORE THE ISSUE OF LETTERS PATENT

Whereas, the undersigned have invented an invention entitled

CHIP-ON-LEAD PACKAGE AND METHOD OF FORMING

for which we make application for letters patent in Malaysia; and

Whereas,

SEMICONDUCTOR COMPONENTS INDUSTRIES L.L.C., (SCI), a Limited Liability Company of the State of Delaware, United States of America, having a principal place of business at 5005 E. McDowell Road, Phoenix, Arizona 85008, United States of America, is desirous of acquiring the said invention and the patent thereto:

Now, therefore, for valuable consideration receipt of which is hereby acknowledged, we by these presents, do sell, assign, and transfer unto SEMICONDUCTOR COMPONENTS INDUSTRIES L.L.C. the full and exclusive right in and to the said invention, as described in the specification executed by us preparatory to obtaining letters patent in Malaysia therefor; said invention, application, and letters patent to be held and enjoyed by the said SEMICONDUCTOR COMPONENTS INDUSTRIES L.L.C. for its own use and behalf and for its legal representatives, to the full end of the term for which said letters patent may be granted, as fully and entirely as the same would have been held by us had this assignment not been made.

We hereby also sell, assign, and transfer unto SCI, the entire right, title, and interest in and to the invention and in and to applications for Letters Patent therefor in all countries foreign to Malaysia, including all rights under any and all international conventions and treaties in respect of the inventions and the applications for Letters Patent in foreign countries, and we further authorize SCI to apply for Letters Patent in foreign countries directly in its own name, and to claim the priority of the filing date of the application for Letters Patent of Malaysia under the provisions of any and all international conventions and treaties.

We hereby authorize and request the Patent Office to issue Letters Patent upon the aforesaid application, division, extension, continuation, or reissue, to SCI, for the sole use and behalf of SCI, its successors, assigns, and legal representatives, to the full end of the term for which the Letters Patent may be granted, the same as they would have been held and enjoyed by us had this assignment not been made, and we hereby authorize and request the equivalent authorities in foreign countries to issue the patents of their respective countries to SCI. We agree that, when requested, we will, without charge to SCI, but at its expense, sign all papers, take all rightful oaths, and do all acts which may be necessary, desirable, or convenient for securing and maintaining patents for the inventions in any and all countries and for vesting title thereto in SCI, its successors, assigns, and legal representatives or nominees.

We covenant with SCI, its successors, assigns, and legal representatives, that the interest and property hereby conveyed is free from all prior assignment, grant, mortgage, license, or other encumbrance.

Executed on the date shown next to my/our name below:

FULL NAME OF FIRST INVENTOR: **Atapol Prajuckamol**

INVENTOR SIGNATURE:  DATE: 3 JAN 2012

RESIDENCE: 32, Soontornwohan Road  
Klaeng, Rayong, Thailand 21110

CITIZENSHIP: Thailand

Witnessed by (Witness signature): 

Printed name of Witness: AZHAR ARI PIN

Date Witnessed: 3 JAN 2012

FULL NAME OF SECOND INVENTOR : **Bih Wen Fon**

INVENTOR SIGNATURE:  DATE: 3/1/2012

RESIDENCE: 88-F, Taman Sentosa  
Bukit Baru, Melaka, Malaysia 75150

CITIZENSHIP: Malaysia

Witnessed by (Witness signature): 

Printed name of Witness: AZHAR ARI PIN

Date Witnessed: 3 JAN 2012

FULL NAME OF THIRD INVENTOR: **Jun Keat Lee**

INVENTOR SIGNATURE:  DATE: 3/1/2012

RESIDENCE: 1078 Jalan TBK 4-2/6  
Taman Bukit Kepayang  
Seremban, Negeri Sembilan, Malaysia 70200

CITIZENSHIP: Malaysia

Witnessed by (Witness signature): 

Printed name of Witness: AZHAR ARI PIN

Date Witnessed: 3 JAN 2012